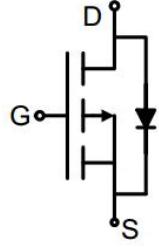


P-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The GT180P10M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} -100V ● I_D (at $V_{GS} = -10V$) -70A ● $R_{DS(ON)}$ (at $V_{GS} = -10V$) < 20mΩ ● $R_{DS(ON)}$ (at $V_{GS} = -4.5V$) < 24mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-263</p>
--	--

Ordering Information			
Device	Package	Marking	Packaging
GT180P10M	TO-263	GT180P10	800pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-100	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	-70	A
	$T_C = 100^\circ\text{C}$		-44	
Pulsed Drain Current	(note1)	I_{DM}	-280	A
Gate-Source Voltage		V_{GS}	± 20	V
Power Dissipation		P_D	210	W
Single pulse avalanche energy	(note2)	E_{AS}	380	mJ
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 To 150	°C

Thermal Resistance				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient		R_{thJA}	50	°C/W
Thermal Resistance, Junction-to-Case		R_{thJC}	0.6	°C/W

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-100	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -100\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -20\text{A}$	--	16	20	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -20\text{A}$	--	18	24	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -20\text{A}$	--	49	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -50\text{V}, f = 1.0\text{MHz}$	--	6000	--	pF
Output Capacitance	C_{oss}		--	500	--	
Reverse Transfer Capacitance	C_{rss}		--	35	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = -50\text{V}, I_D = -20\text{A}, V_{\text{GS}} = -10\text{V}$	--	92	--	nC
Gate-Source Charge	Q_{gs}		--	16	--	
Gate-Drain Charge	Q_{gd}		--	12	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -50\text{V}, I_D = -20\text{A}, R_G = 1.6\Omega$	--	22	--	ns
Turn-on Rise Time	t_r		--	18	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	80	--	
Turn-off Fall Time	t_f		--	22	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	-70	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = -20\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	-1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = -20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = -100\text{A}/\text{us}$	--	160	--	nC
Reverse Recovery Time	T_{rr}		--	88	--	ns

Notes

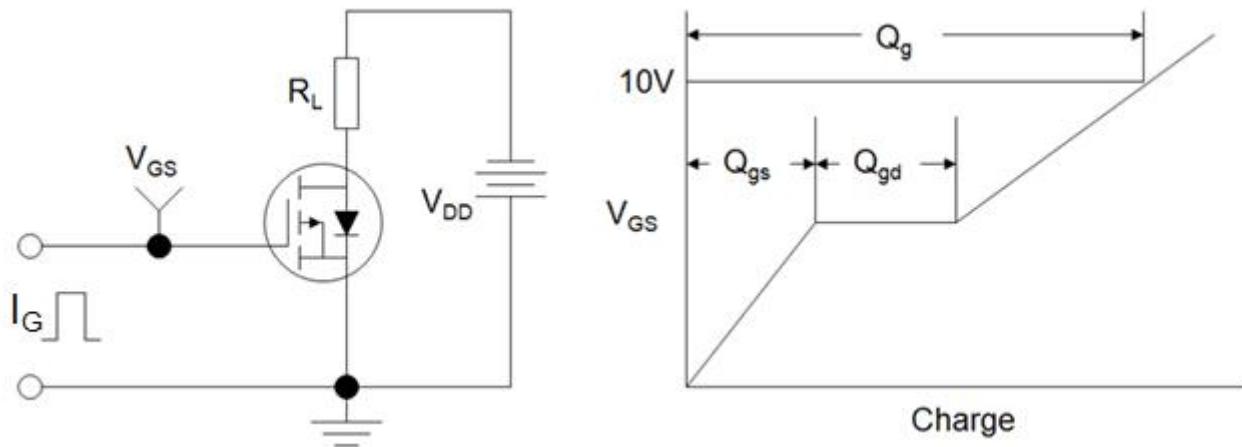
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$

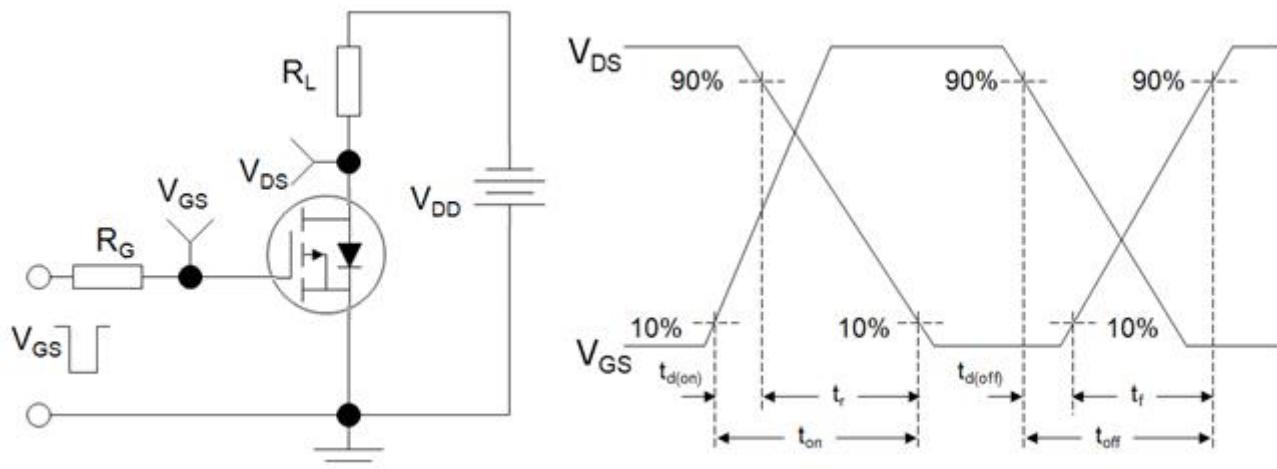
The table shows the minimum avalanche energy, which is 1056mJ when the device is tested until failure

3. Identical low side and high side switch with identical R_g

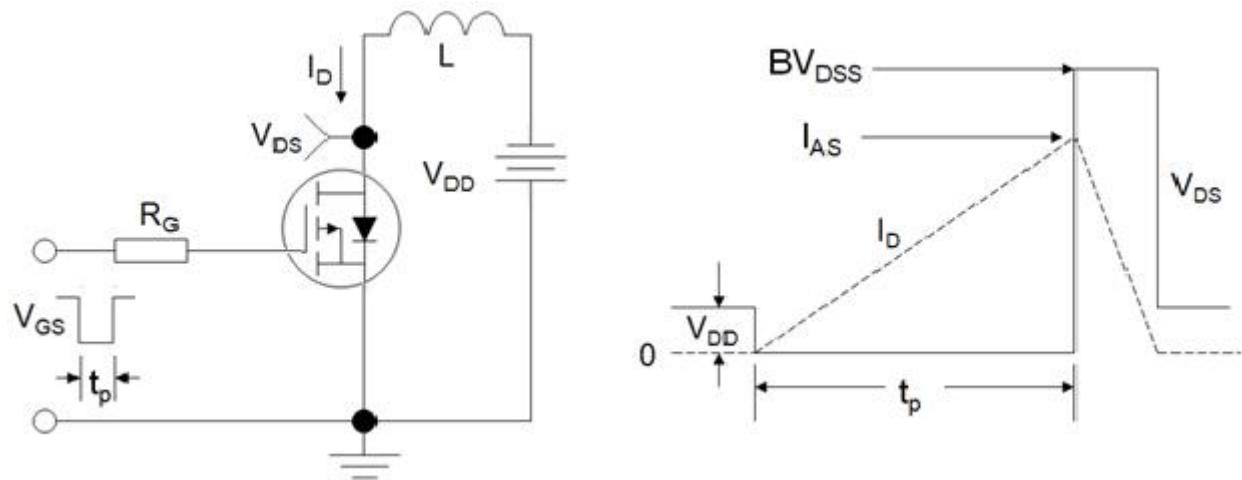
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

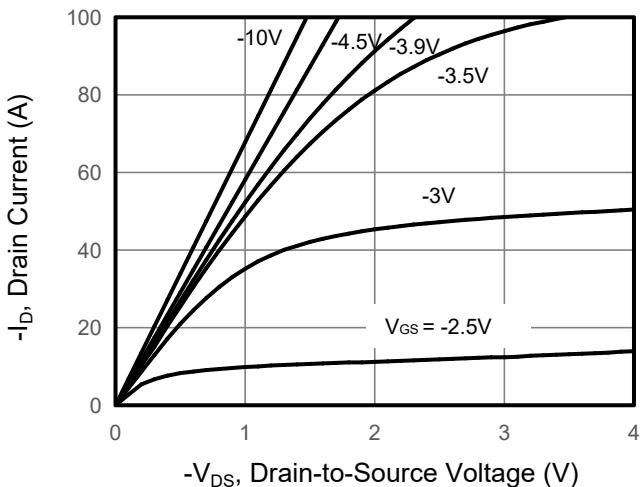


Figure 2. Transfer Characteristics

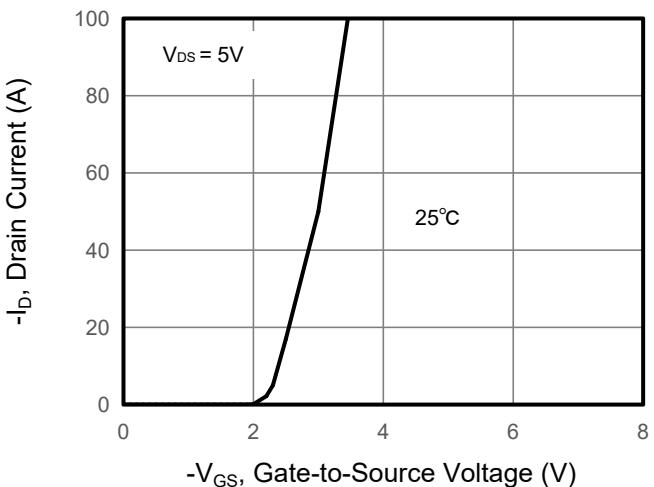


Figure 3. Drain Source On Resistance

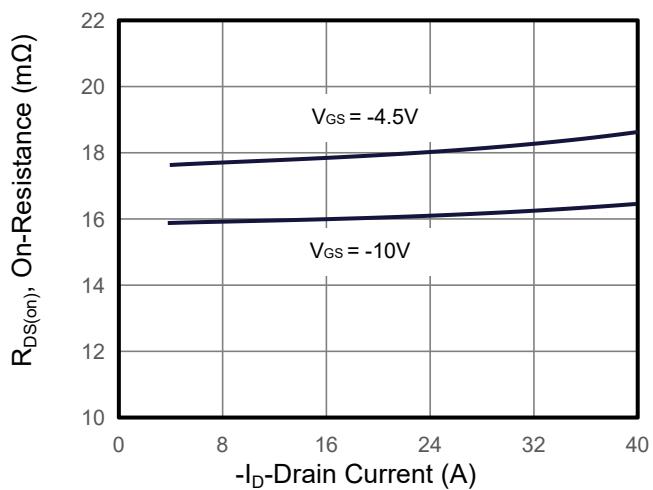


Figure 4. Gate Charge

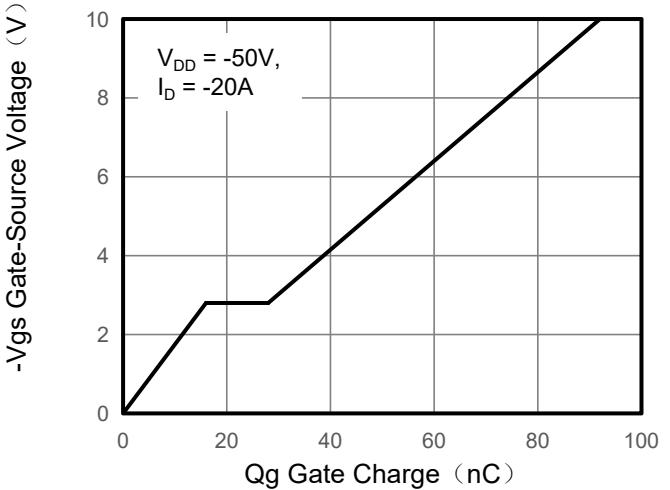


Figure 5. Capacitance

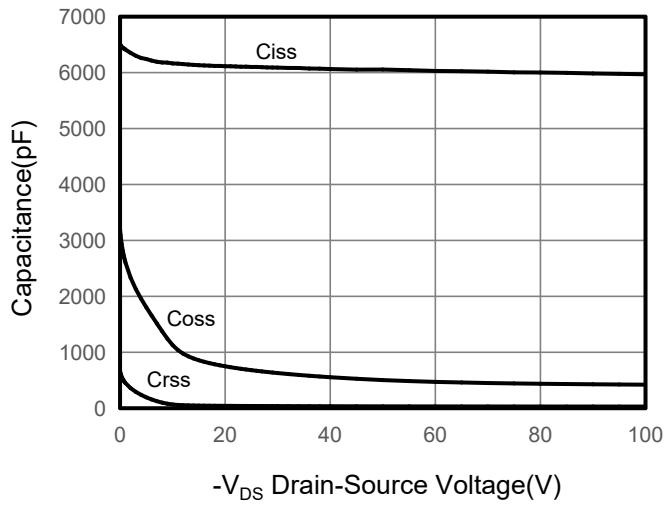
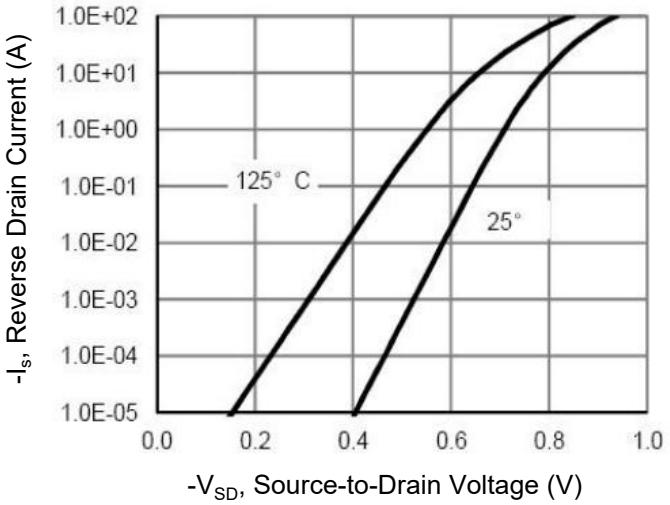


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

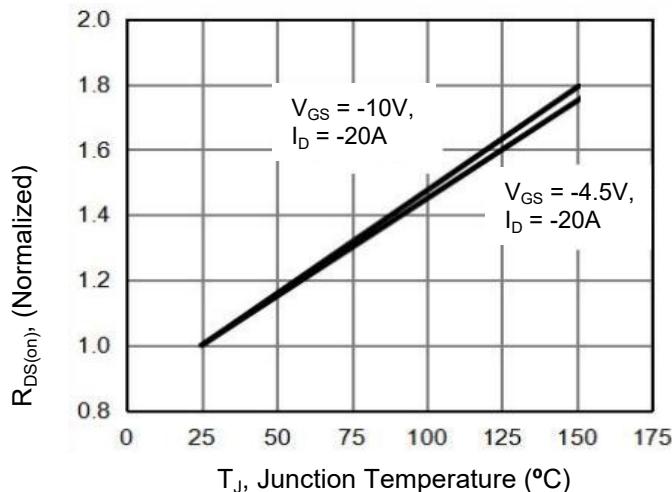


Figure 8. Safe Operation Area

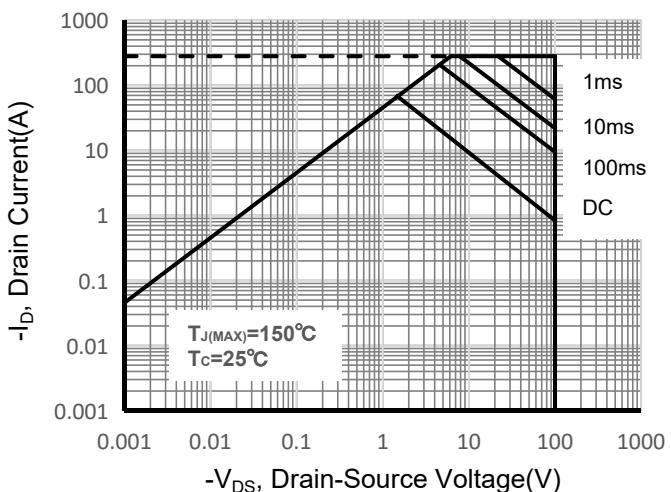


Figure 9. Maximum Continuous Drain Current vs Case Temperature

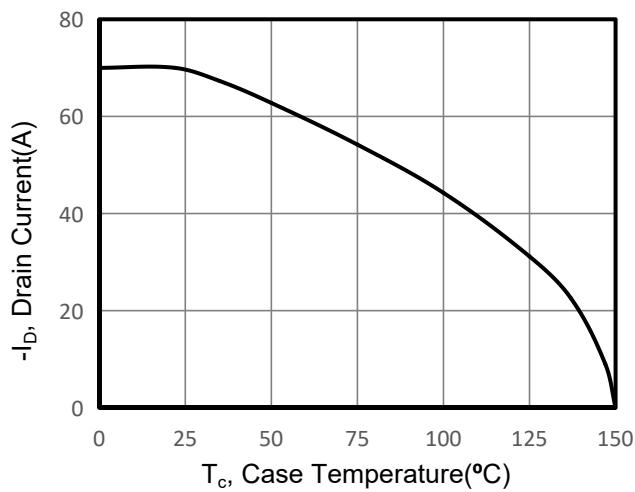
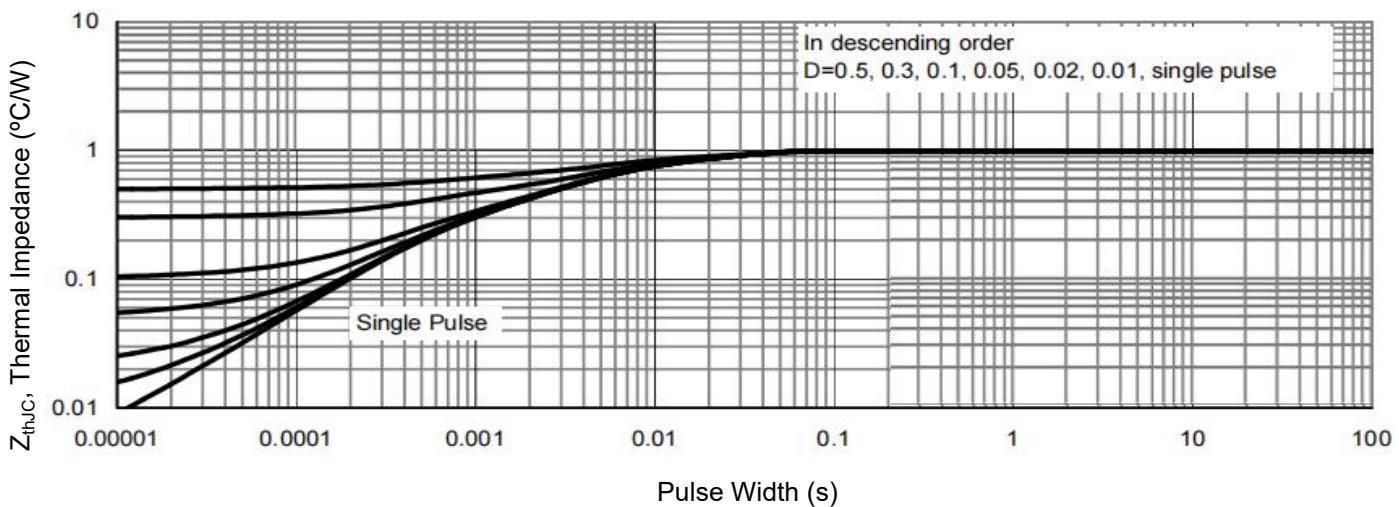
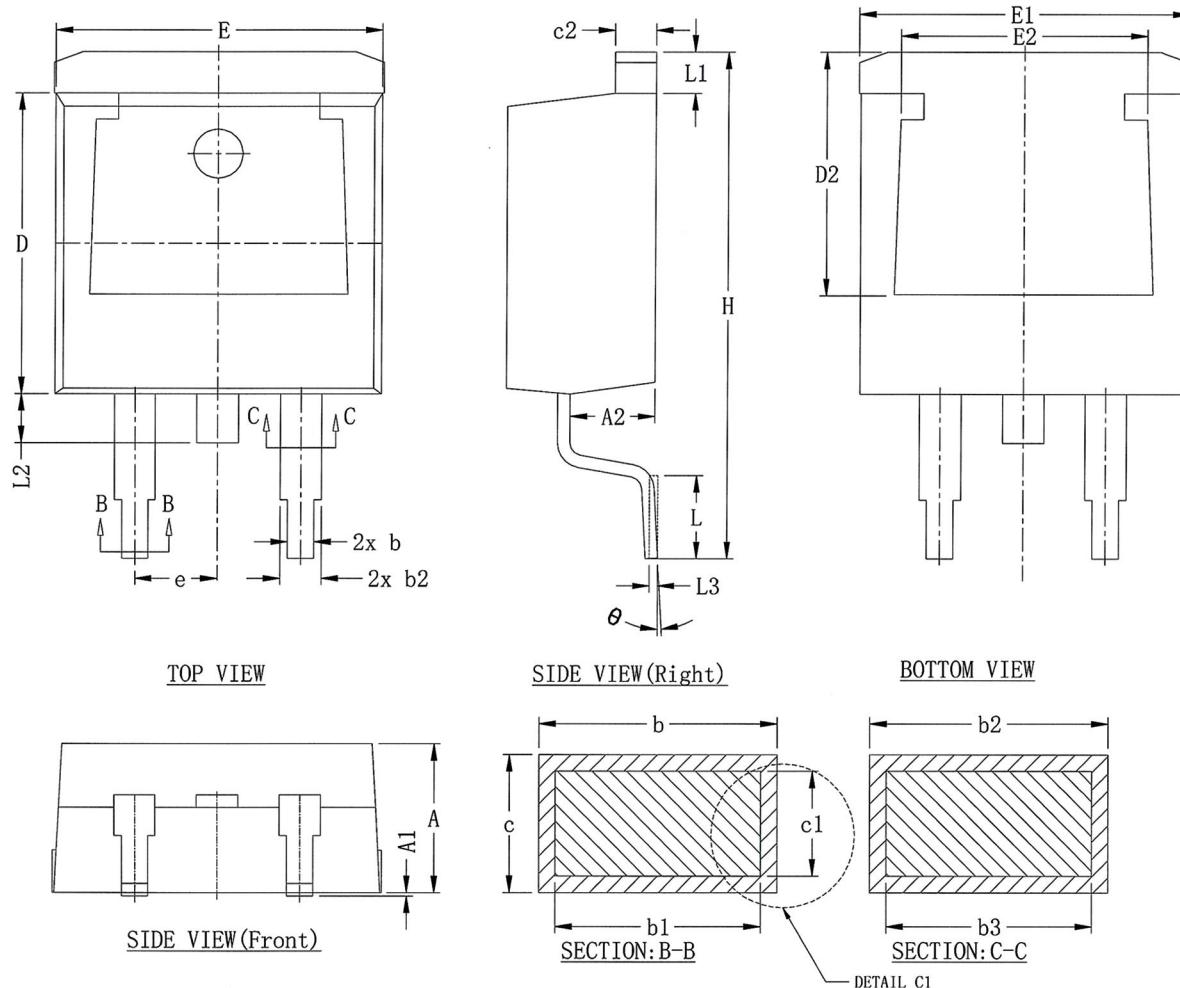


Figure 10. Normalized Maximum Transient Thermal Impedance



TO-263 Package Information



DIM SYMBOL	MIN.	NOM.	MAX.	DIM SYMBOL	MIN.	NOM.	MAX.
A	4.450	4.550	4.650	D2	7.215	7.415	7.615
A1	0.000	—	0.150	E	9.900	10.000	10.100
A2	2.500	2.600	2.700	E1	9.900	10.100	10.300
b	0.753	0.853	0.953	E2	7.341	7.541	7.741
b1	0.713	0.813	0.913	e	2.540 BSC.		
b2	1.210	1.310	1.410	H	15.300	15.500	15.700
b3	1.170	1.270	1.370	L	2.340	2.540	2.740
c	0.330	0.421	0.521	L1	1.066	1.266	1.466
c1	0.281	0.381	0.481	L2	1.400	1.500	1.600
c2	1.210	1.310	1.410	L3	0.254 BSC.		
D	9.100	9.200	9.300	θ	0°	---	5°